Please amend the specification as follows:

In the Claims:

B1

1. (Twice Amended) A semiconductor device comprising:

a semiconductor chip upon which are disposed roughly upon a straight line a plurality of bonding pads, each of said bonding pads containing a first region as a connection region and a second region for making contact with a testing probe, and said first and second regions are lined up in a direction substantially perpendicular to said straight line, wherein said plurality of bonding pads comprises a first group of bonding pads with said first regions in a first direction and said second regions in a second direction, and a second group of bonding pads provided with said second regions in said first direction and said first regions in said second direction,

a member provided with a plurality of conductors containing a third region as a connection region electrically connected to each of a plurality of external connection terminals and a securing area for securing said semiconductor chip,

a plurality of conductor wires that electrically connect said first regions of said plurality of bonding pads to said third regions of said plurality of conductors, and

an encapsulating member that encapsulates said semiconductor chip and said plurality of conductor wires.

B2

2. (Amended) The semiconductor device according to claim 1 wherein said first and second groups of bonding pads are alternately arranged.

B3

3. (Twice Amended) The semiconductor device according to claim 1 wherein said plurality of bonding pads are rectangular in shape with their short sides lying in a direction along the edges of said semiconductor chip.

B4

7. (Twice Amended) A method of manufacturing semiconductor devices comprising:

disposing roughly upon a straight line on a semiconductor chip a plurality of bonding pads containing a first region as a connection region and a second region for making contact with a testing probe, and said first and second regions are lined up in a direction perpendicular to said straight line, wherein said plurality of bonding pads comprises a first group of bonding pads with said first regions in a first direction and said second regions in a second direction, and a second group of bonding pads provided with said second regions in said first direction and said first regions in said second direction,

providing a member with a plurality of conductors containing a third region as a connection region electrically connected to each of a plurality of external connection terminals, and a securing area for securing said semiconductor chip, and

disposing a plurality of conductor wires to electrically connect said first regions of said plurality of bonding pads to said third regions of said plurality of conductors.

8. (Amended) The method of manufacturing semiconductor devices according to claim 7 wherein said first and second groups of bonding pads are alternately arranged.

10. (Twice Amended) The method of manufacturing semiconductor devices according to claim 7 further comprising a step wherein, prior to securing said semiconductor chip to said securing area, testing of said semiconductor chip is performed by putting test probes into contact with the second regions of said plurality of bonding pads.

18. (Amended) The method of manufacturing semiconductor devices according to claim 8 further comprising a step wherein, prior to securing said semiconductor chip to said securing area, testing of said semiconductor chip is performed by putting test probes into contact with the second regions of said plurality of bonding pads.